

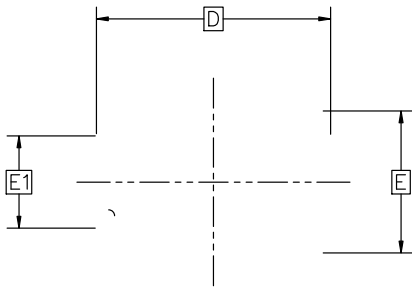


SOIC 16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

DATE 18 OCT 2024

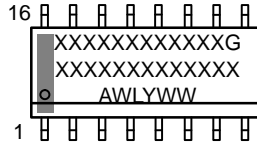
- 3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 4. MAXIMUM MOLD PROTRUSION 0.17

b DIMENSION AT MAXIMUM MATE nm TOTAL IN EXCESS OF THE



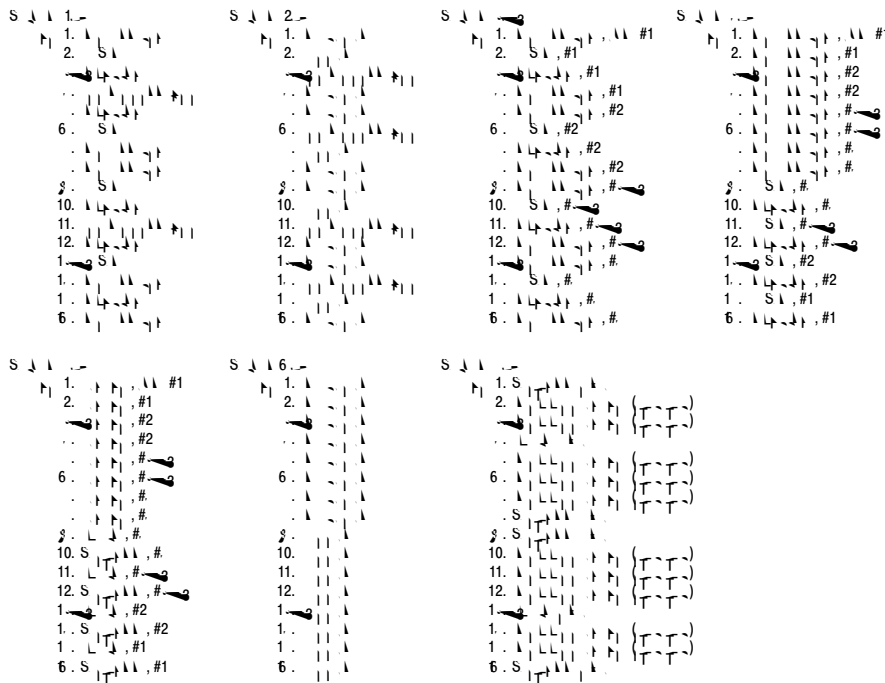
TOP VIEW

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



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